

Axiom Electronics PCBA Design for Manufacturability Guidelines

Section: 10.4

Revision: A

Revision Date: 2/14/13

DFM Subject: Mounting Holes Used For Grounding

DFM Requirement:

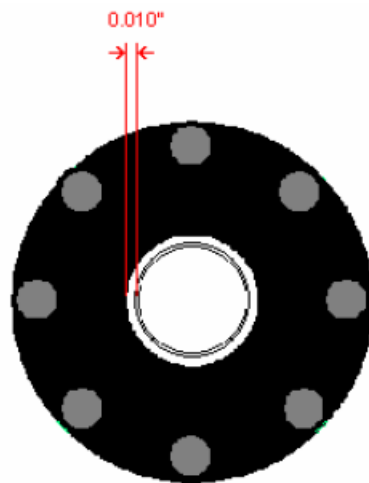
Mounting holes that are used for Grounding shall use a spoke pattern instead of a standard plated through hole with an annular ring.

- The pad on the primary side of the pattern shall be 0.25mm (0.010") from the outside diameter of the drilled hole.
- The traces on the secondary side of the spoke pattern shall be 0.25mm (0.010") from the outside diameter of the drilled hole. The minimum trace width is 1.27mm (0.050").
- The vias drilled in the ring shall not be smaller than 31DR18.
- The outside diameter of the primary and secondary side patterns shall be equal to or greater than the maximum diameter of the hardware being used.
- The center mounting or tooling holes shall not be plated through.
- Soldermask shall not cover the pattern on either side of the PCB.

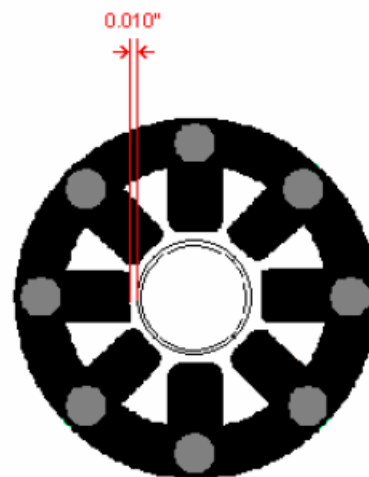
DFM Impact:

This pattern allows for selective soldering to be done without temporary masking.

DFM Details:



Primary Side Pattern



Secondary Side Pattern